



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-04-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	FLORIANA SAN BIAGIO	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	MAEC*UAH5ADT	A	Z6HA	2017-04-07
Amount	UoM	Unit type	ST ECOPACK Grade	
42.00	mg	Each	ECOPACK® 2	
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
tin is used or other bulk terminati	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	4x4x1	28	No lead	
Comment	Package: AOEC VFQFPN 28L 4X4X1 0,4 PITCH; MDF valid for PM6764TR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MAEC*UAH5ADT					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.832	mg	supplier	die	Silicon (Si)	7440-21-3		4.644	mg	961093	110571
				supplier	metallization	Aluminium (Al)	7429-90-5		0.046	mg	9520	1095
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	207	24
				supplier	metallization	Titanium (Ti)	7440-32-6		0.004	mg	828	95
				supplier	metallization	Tungsten (W)	7440-33-7		0.004	mg	828	95
				supplier	Passivation	Silicon Nitride	12033-89-5		0.013	mg	2690	310
				supplier	Passivation	Silicon Oxide	7631-86-9		0.088	mg	18212	2095
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.004	mg	828	95
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	1863	214
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	3725	429
Leadframe	Copper & its alloys	26.890	mg	supplier	alloy	Copper (Cu)	7440-50-8		25.902	mg	963258	616714
				supplier	alloy	Iron (Fe)	7439-89-6		0.607	mg	22573	14452
				supplier	alloy	Phosphorus (P)	12185-10-3		0.007	mg	260	167
				supplier	alloy	Zinc (Zn)	7440-66-6		0.034	mg	1264	810
				supplier	metallization	Nickel (Ni)	7440-02-0		0.309	mg	11491	7357
				supplier	metallization	Palladium (Pd)	7440-05-3		0.027	mg	1004	643
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	149	95
				supplier	metallization	Silver (Ag)	7440-22-4		0.343	mg	803279	8167
Die attach	Other Organic Materials	0.427	mg	supplier	glue	Carbocyclic Acrylates	proprietary		0.043	mg	100703	1024
				supplier	glue	Bismaleimide	35325-39-4		0.013	mg	30445	310
				supplier	glue	2-preponoic acid, 2-methy	68586-19-6		0.013	mg	30445	310
				supplier	glue	Additive	proprietary		0.013	mg	30445	310
				supplier	glue	Dicumyl peroxide	80-43-3		0.002	mg	4684	48
				supplier	wire	Copper (Cu)	7440-50-8		0.084	mg	976744	2000
Bonding wires	Other inorganic materials	0.086	mg	supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	23256	48
				supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	23256	48
Encapsulation	Other Organic Materials	9.766	mg	supplier	mold compound	Silica Fused	60676-86-0		9.151	mg	937026	217881
				supplier	mold compound	Epoxy Resin	25068-38-6		0.293	mg	30002	6976
				supplier	mold compound	Phenol Resin	29690-82-2		0.293	mg	30002	6976
				supplier	mold compound	Carbon Black	1333-86-4		0.029	mg	2969	690